

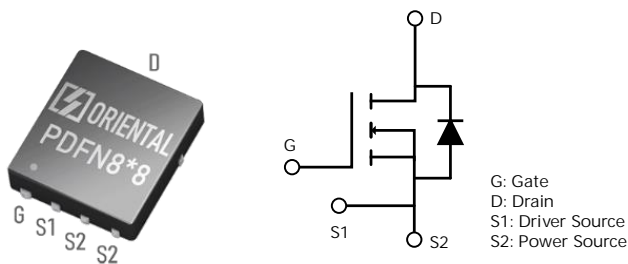
The GreenMOS<sup>®</sup> high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.



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Parameter	Value	Unit
$V_{DS, min} @ T_{j(max)}$	650	V
$I_{D, pulse}$	99	A
$R_{DS(ON), max} @ V_{GS}=10V$	74	
$Q_g$	68.6	nC

Product Name	Package	Marking
OSG60R074JT3ZF	PDFN 8x8	OSG60R074JT3Z



**Absolute Maximum Ratings** at  $T_j=25$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{DS}$	600	V
Gate-source voltage	$V_{GS}$	$\pm 30$	V
Continuous drain current <sup>1)</sup> , $T_C=25$ °C	$I_D$	33	A
Continuous drain current <sup>1)</sup> , $T_C=100$ °C		20.9	
Pulsed drain current <sup>2)</sup> , $T_C=25$ °C	$I_{D, pulse}$	99	A
Continuous diode forward current <sup>1)</sup> , $T_C=25$ °C	$I_S$	33	A
Diode pulsed current <sup>2)</sup> , $T_C=25$ °C	$I_{S, pulse}$	99	A
Power dissipation <sup>3)</sup> , $T_C=25$ °C	$P_D$	187	W
Single pulsed avalanche energy <sup>5)</sup>	$E_{AS}$	640	mJ
MOSFET dv/dt ruggedness, $V_{DS}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}$	dv/dt	50	V/ns
Operation and storage temperature	$T_{stg}, T_j$	-55 to 150	°C

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	R	0.67	°C/W
Thermal resistance, junction-ambient <sup>4)</sup>	R	62	°C/W

**Electrical Characteristics** at  $T_j=25$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	$BV_{DSS}$	600			V	$V_{GS}=0$ V, $I_D=1$ mA
		650				$V_{GS}=0$ V, $I_D=1$ mA, $T_j=150$ °C
Gate threshold voltage	$V_{GS(th)}$	3.0		5.0	V	$V_{DS}=V_{GS}$ , $I_D=1$ mA
Drain-source on-state resistance	$R_{DS(ON)}$		60	74	m	$V_{GS}=10$ V, $I_D=15.1$ A
			146			$V_{GS}=10$ V, $I_D=15.1$ A, $T_j=150$ °C
Gate-source leakage current	$I_{GSS}$			100	nA	$V_{GS}=30$ V
				-100		$V_{GS}=-30$ V
Drain-source leakage current	$I_{DSS}$			10	A	$V_{DS}=600$ V, $V_{GS}=0$ V
Gate resistance	$R_G$		8.8			

### Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	$C_{iss}$		3340		pF	$V_{GS}=0\text{ V}$ , $V_{DS}=50\text{ V}$ , 100 kHz
Output capacitance	$C_{oss}$		177		pF	
Reverse transfer capacitance	$C_{rss}$		4.1		pF	
Effective output capacitance, energy related	$C_{o(er)}$		112		pF	$V_{GS}=0\text{ V}$ , $V_{DS}=0\text{ V}-400\text{ V}$
Effective output capacitance, time related	$C_{o(tr)}$		662		pF	
Turn-on delay time	$t_{d(on)}$		31		ns	$V_{GS}=10\text{ V}$ , $V_{DS}=400\text{ V}$ , $R_G$ $I_D=20\text{ A}$
Rise time	$t_r$		44.2		ns	
Turn-off delay time	$t_{d(off)}$		88		ns	
Fall time	$t_f$		26.2		ns	

### Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	$Q_g$		68.6		nC	$V_{GS}=10\text{ V}$ , $V_{DS}=400\text{ V}$ , $I_D=20\text{ A}$
Gate-source charge	$Q_{gs}$		22.1		nC	
Gate-drain charge	$Q_{gd}$		22.7		nC	
Gate plateau voltage	$V_{plateau}$		6.8		V	

### Body Diode Characteristics

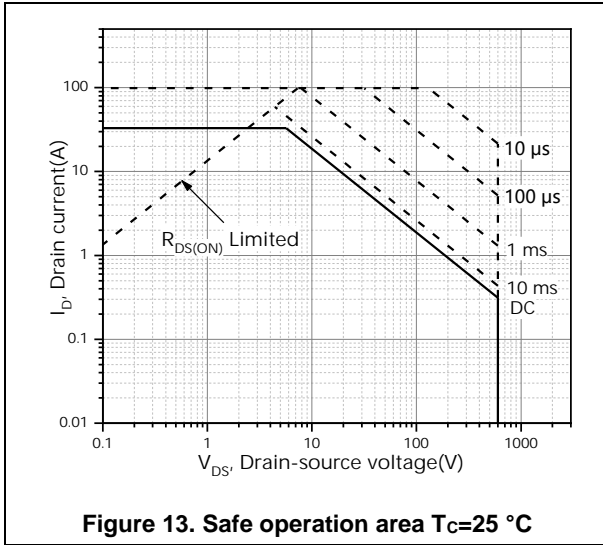
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	$V_{SD}$			1.3	V	$I_S=33\text{ A}$ , $V_{GS}=0\text{ V}$
Reverse recovery time	$t_{rr}$		156		ns	$V_R=400\text{ V}$ , $I_S=20\text{ A}$ , $di/dt=10$
Reverse recovery charge	$Q_{rr}$		0.9		uC	
Peak reverse recovery current	$I_{rrm}$		11.3		A	

### Note

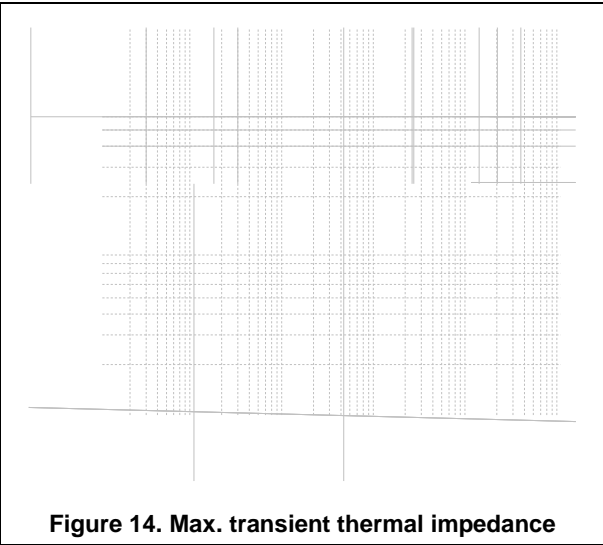
- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3)  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of  $R_{\theta}$  is measured with the device mounted on 1 in square FR-4 board with 2oz. Copper, in a still air environment with  $T_a=25\text{ °C}$ .
- 5)  $V_{DD}=100\text{ V}$ ,  $V_{GS}=10\text{ V}$ ,  $L=80\text{ mH}$ , starting  $T_j=25\text{ °C}$ .

Enhancement Mode N-



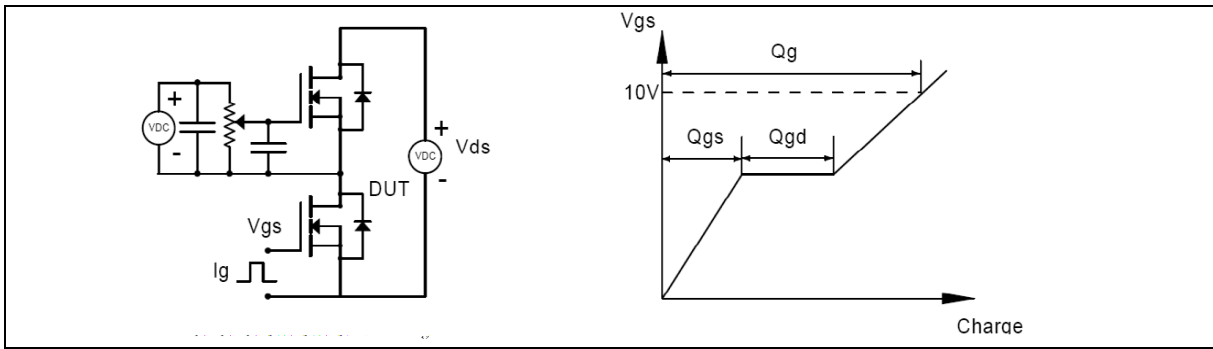


**Figure 13. Safe operation area  $T_c=25^\circ\text{C}$**

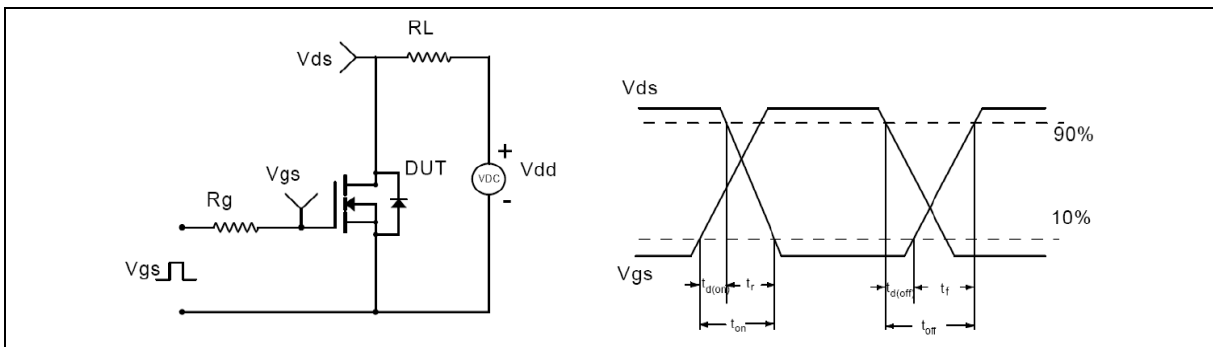


**Figure 14. Max. transient thermal impedance**

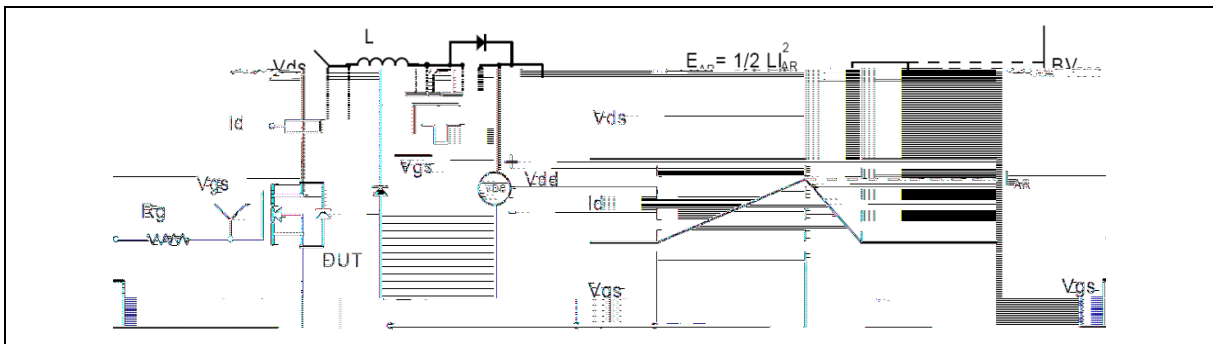
**Test circuits and waveforms**



**Figure 1. Gate charge test circuit & waveform**



**Figure 2. Switching time test circuit & waveforms**

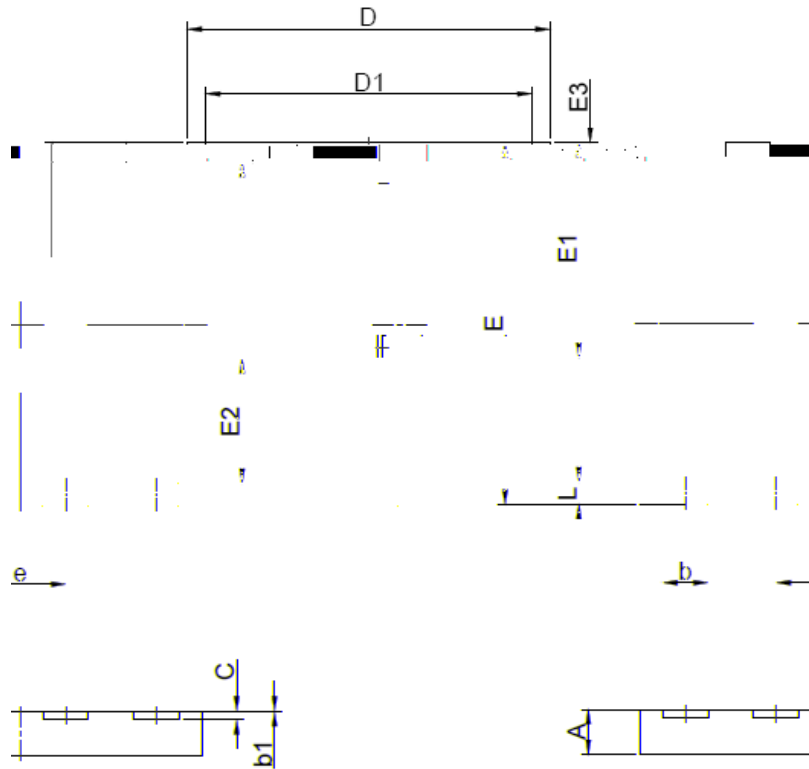


**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**



**Figure 4. Diode reverse recovery test circuit & waveforms**

**Package Information**

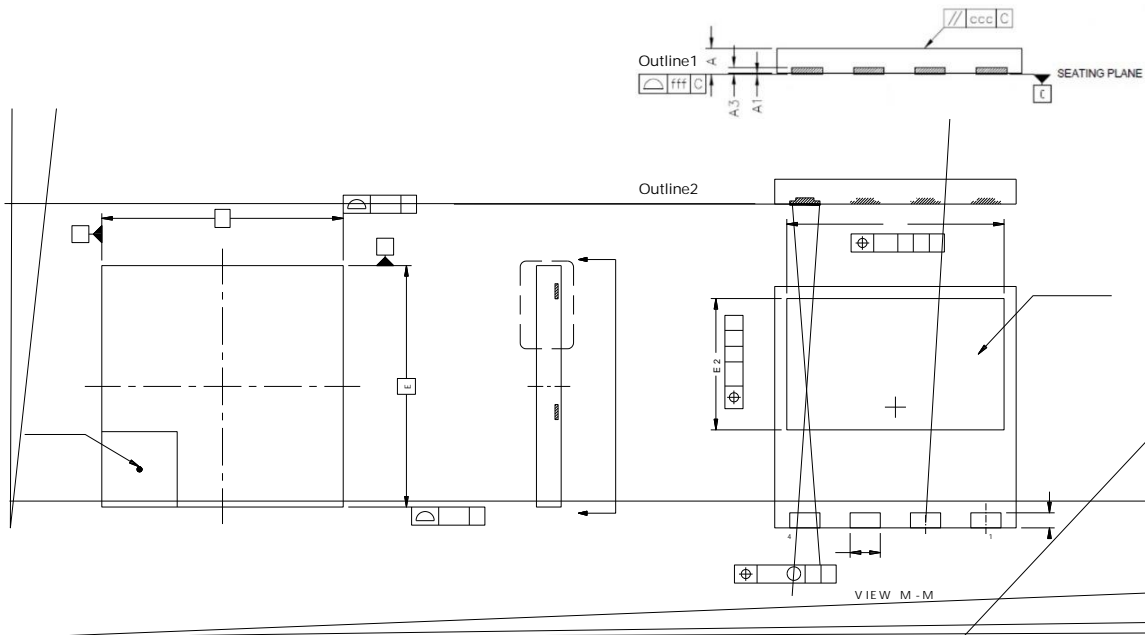


Symbol	mm		
	Min	Nom	Max
A	0.90	1.00	1.10
b	0.90	1.00	1.10
b1	0.00	0.02	0.05
C	0.2 REF		
D	7.90	8.00	8.10
D1	7.10	7.20	7.30
E	7.90	8.00	8.10
E1	4.65	4.75	4.85
E2	2.65	2.75	2.85
E3	0.3	0.4	0.5
e	2.0 BSC		
L	0.4	0.5	0.6

Version 1: PDFN 8x8-L package outline dimension



**Package Information**



Symbol	mm	
	Min	Max
A	0.75	0.95
A1	0.00	0.05
A3	0.10	0.30
b	0.90	1.10
D	7.90	8.10
E	7.90	8.10
D2	7.10	7.30
E1	2.65	2.85
E2	4.25	4.45
e	2.0 BSC	
L	0.40	0.60
aaa	0.1	
ggg	0.05	
ccc	0.05	
fff	0.05	

Version 2: PDFN 8x8-S package outline dimension

